Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled)

2. (Currently Amended) A semiconductor device, comprising:

a substrate including an electrode electrically connected to at least one integrated circuit;

a resin layer formed on the side of the substrate where the electrode is formed, avoiding the location of the electrode;

an interconnection layer extending from the electrode to an upper surface of the resin layer and including at least one land formed on the resin layer;

an external terminal being provided on the land and electrically connected to the electrode;

a light transmissive insulation layer disposed on the external terminal side of the ~~substrate;~~substrate, the insulation layer being formed to cover the interconnection layer with at least a part of the external terminal exposed; and

a mark provided on the substrate and covered by the light transmissive insulation layer so as to be visible through the insulation layer,

wherein the substrate is a semiconductor substrate, and the integrated circuit is formed on the semiconductor substrate.

3. (Canceled)

4. (Currently Amended) The semiconductor device according to ~~claim 3,~~ claim 2, the mark being provided on the resin layer.

5. (Currently Amended) The semiconductor device according to ~~claim 3,~~ claim 2, further comprising:

a passivation film provided on the semiconductor substrate,

the mark being provided on the passivation film.

6. (Currently Amended) The semiconductor device according to ~~claim 3,~~ claim 2, the mark being made of the same material as at least a part of the material which the interconnection layer is made of.

7. (Currently Amended) The semiconductor device according to ~~claim 3,~~ claim 2, the mark being provided on an area not in contact with the interconnection layer.

8. (Currently Amended) The semiconductor device according to ~~claim 3,~~ claim 2, the interconnection layer having a plurality of lands including a first land having a shape incorporating the mark and a second land having a shape different from the shape of the first land.

9. (Previously Presented) The semiconductor device according to claim 2, the external terminal being a solder ball, and the insulation layer being a solder resist.

10. (Previously Presented) The semiconductor device according to claim 2, the semiconductor substrate being a semiconductor chip.

11. (Original) The semiconductor device according to claim 10, the mark being provided on at least one of the four corners of the semiconductor chip.

12. (Previously Presented) The semiconductor device according to claim 2, the semiconductor substrate being a semiconductor wafer including the integrated circuit for each of plural areas.

13. (Currently Amended) A circuit board, comprising a semiconductor device, the semiconductor device, comprising:

a substrate including an electrode electrically connected to at least one integrated circuit;

a resin layer formed on the side of the substrate where the electrode is formed, avoiding the location of the electrode;

an interconnection layer extending from the electrode to an upper surface of the resin layer and including at least one land formed on the resin layer;

an external terminal being provided on the land and electrically connected to the electrode;

a light transmissive insulation layer disposed on the external terminal side of the ~~substrate;~~ substrate, the insulation layer being formed to cover the interconnection layer with at least a part of the external terminal exposed; and

a mark provided on the substrate and covered by the light transmissive insulation layer so as to be visible through the insulation layer.

14. (Previously Presented) An electronic apparatus, comprising a circuit board according to claim 13.

15. (Currently Amended) A method of mounting a semiconductor device, comprising a substrate including an electrode electrically connected to at least one integrated circuit; a resin layer formed on the side of the substrate where the electrode is formed, avoiding the location of the electrode; an interconnection layer extending from the electrode to an upper surface of the resin layer and including at least one land formed on the resin layer; an external terminal being provided on the land and electrically connected to the electrode; a light transmissive insulation layer disposed on the external terminal side of the ~~substrate;~~ substrate, the insulation layer being formed to cover the interconnection layer with at least a part of the external terminal exposed; and a mark provided on the substrate and covered by the light transmissive insulation layer so as to be visible through the insulation layer, onto a circuit board, the method ~~comprising~~ comprising:

determining a mounting orientation of the semiconductor device by recognizing the mark through the insulation layer.

16. (Canceled)